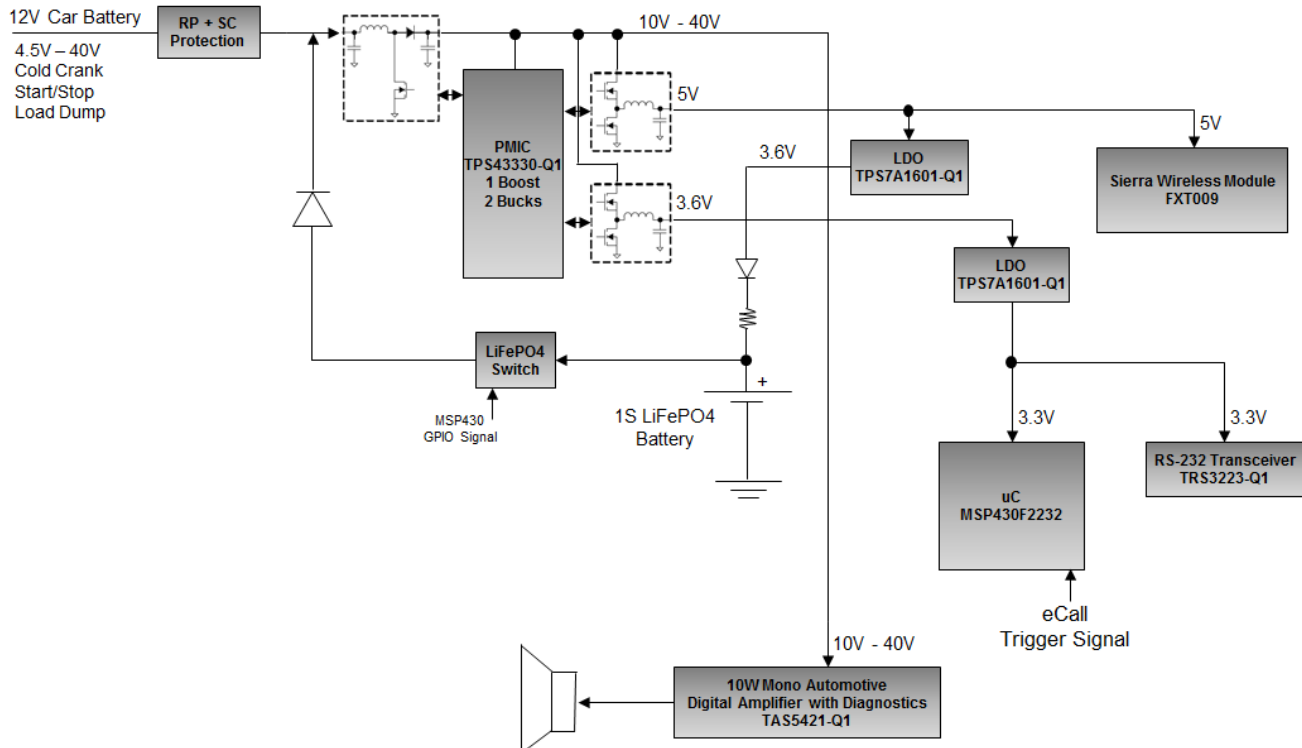


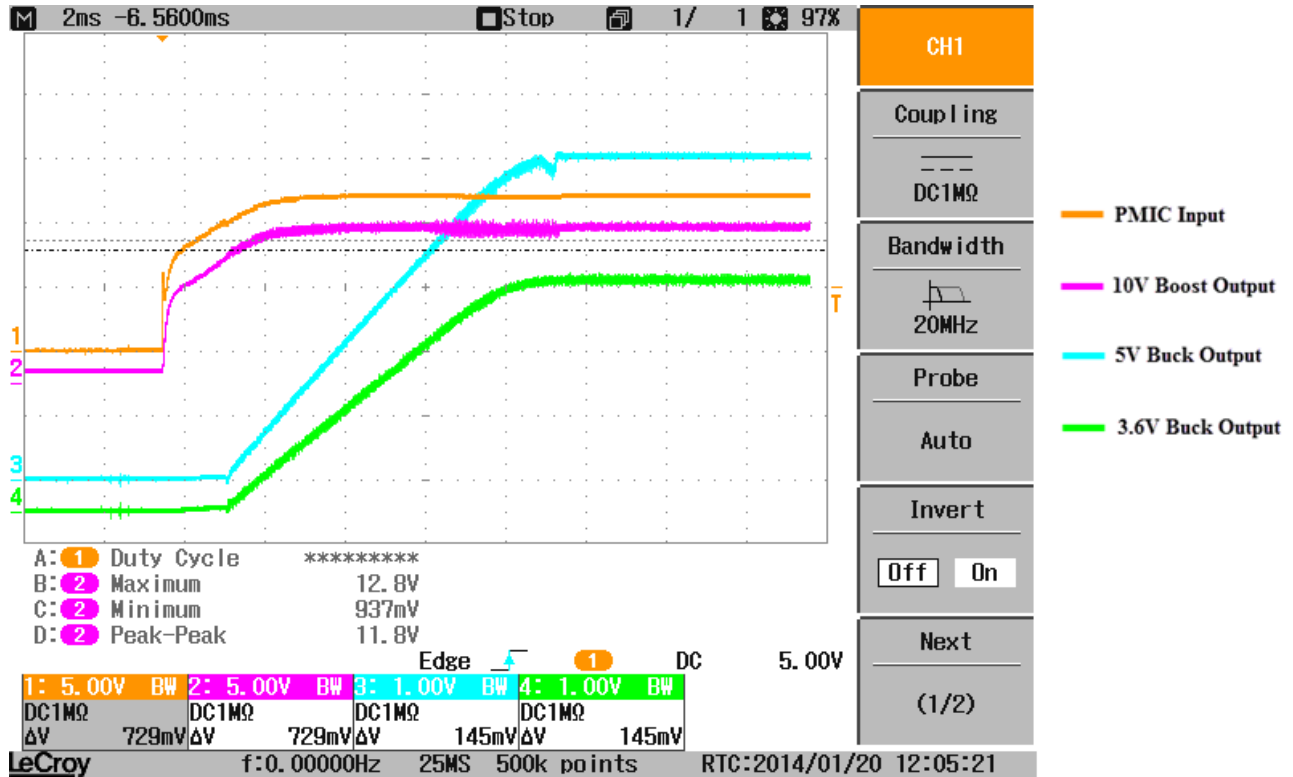
The following items are included in this test report:

- A. Startup Power Sequence off 12V Power Supply
- B. Call off 12V Power Supply
- C. 12V Power Supply Disconnected
- D. Short to Ground off Backup Cell Battery
- E. Call off Backup Cell Battery
- F. 12V Power Supply Reconnected



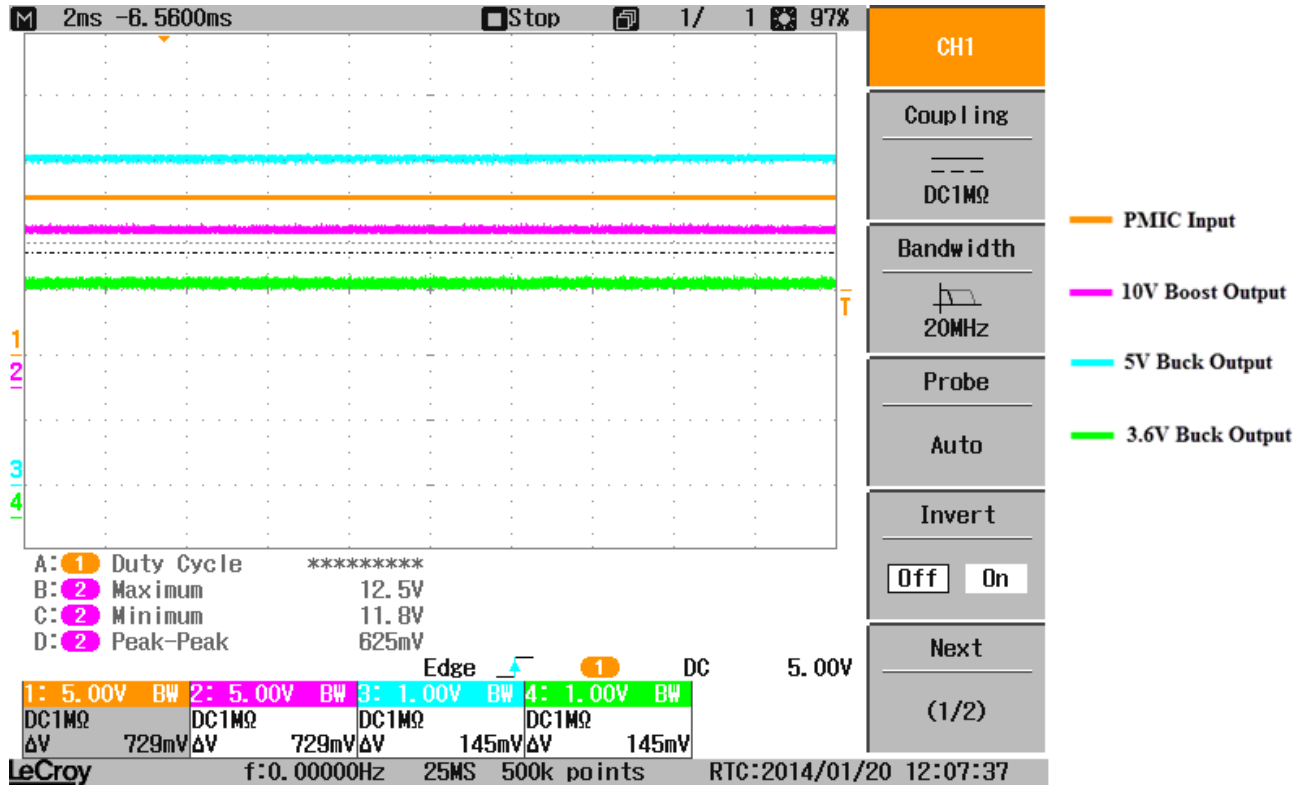
## A. Startup Power Sequence off 12V Power Supply

The following waveforms illustrate the startup sequence of the PMIC Input, 10V Boost Converter Output, 5V Buck Converter Output, and 3.6V Buck Converter Output after a 12V Power Supply was connected to J6.



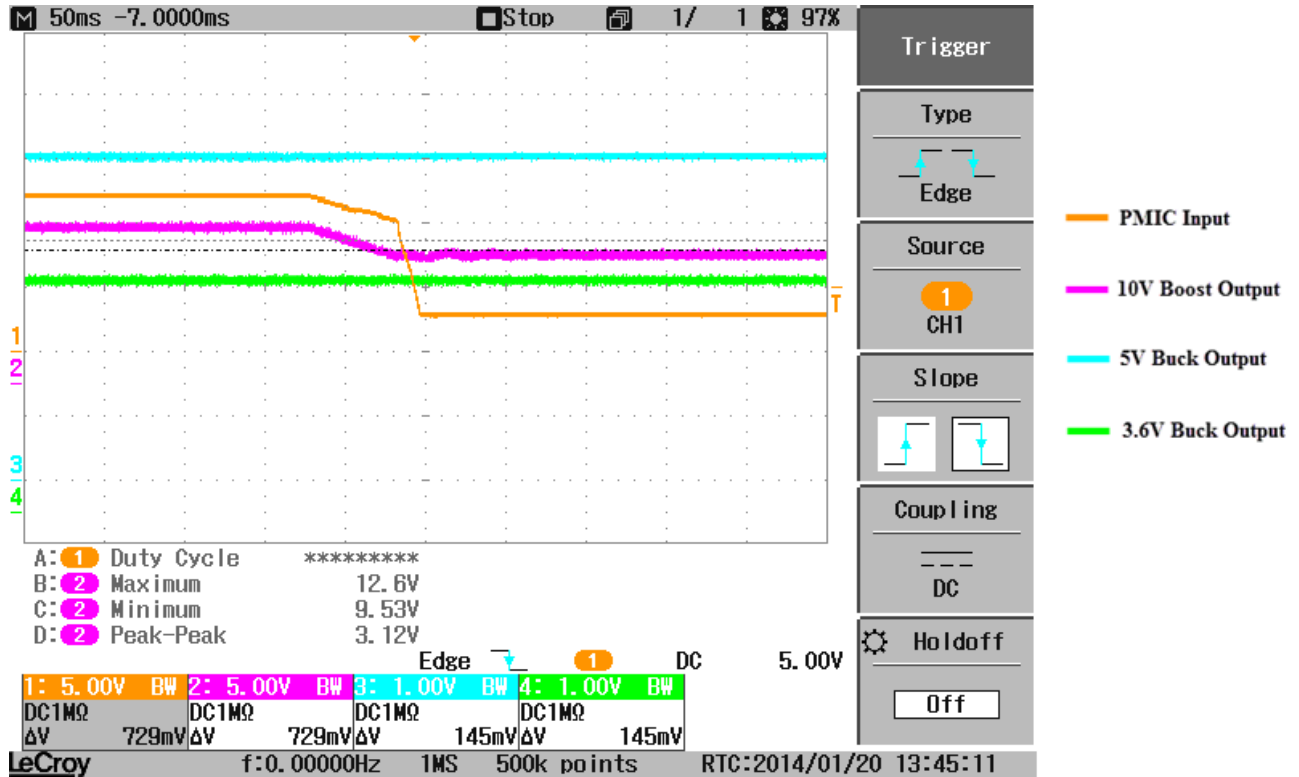
## B. Call off 12V Power Supply

The following waveforms illustrate the PMIC Input, 10V Boost Converter Output, 5V Buck Converter Output, and 3.6V Buck Converter Output after a call was placed with the 12V Power Supply connected to J6.



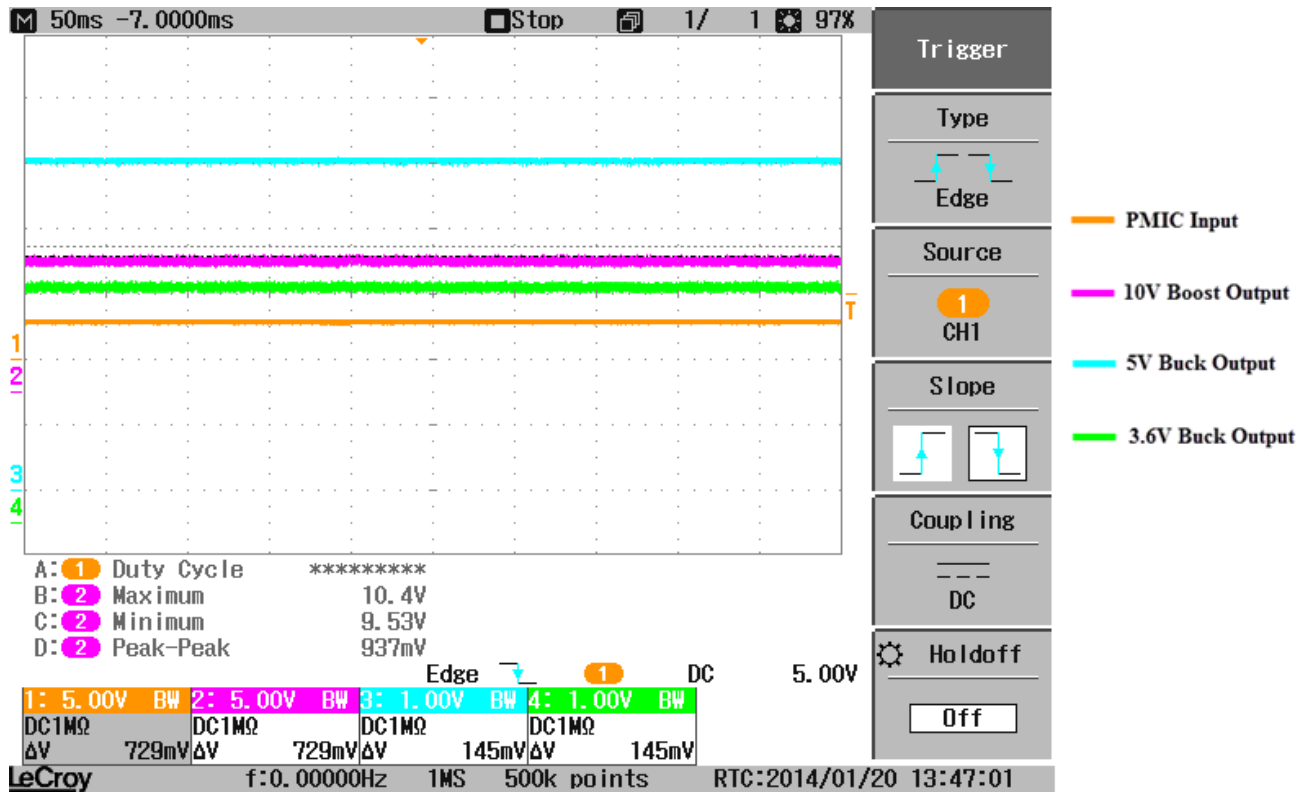
## C. 12V Power Supply Disconnected

The following waveforms illustrate the PMIC Input, 10V Boost Converter Output, 5V Buck Converter Output, and 3.6V Buck Converter Output after the 12V Power Supply was disconnected from J6.



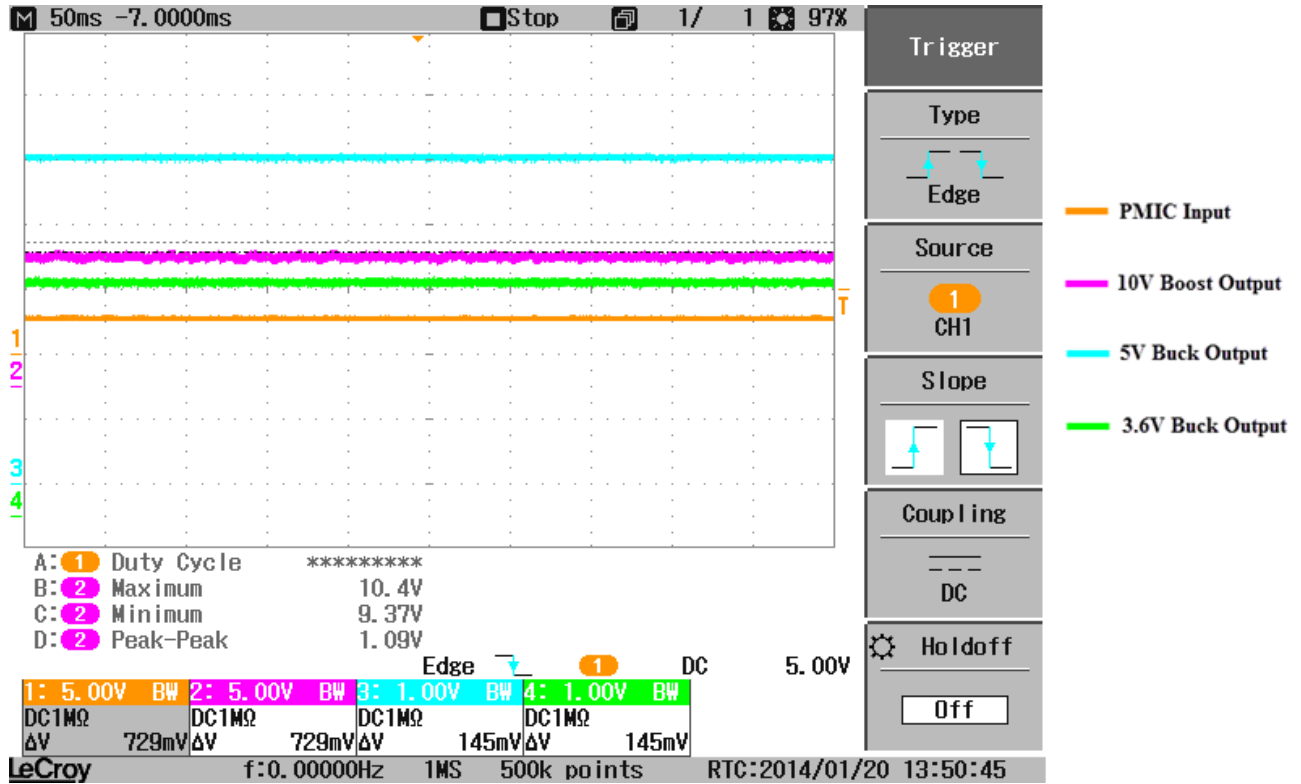
## D. Short to Ground off Backup Cell Battery

The following waveforms illustrate the PMIC Input, 10V Boost Converter Output, 5V Buck Converter Output, and 3.6V Buck Converter Output while TP8 (car battery connection) was shorted to ground during operation off the backup cell battery.



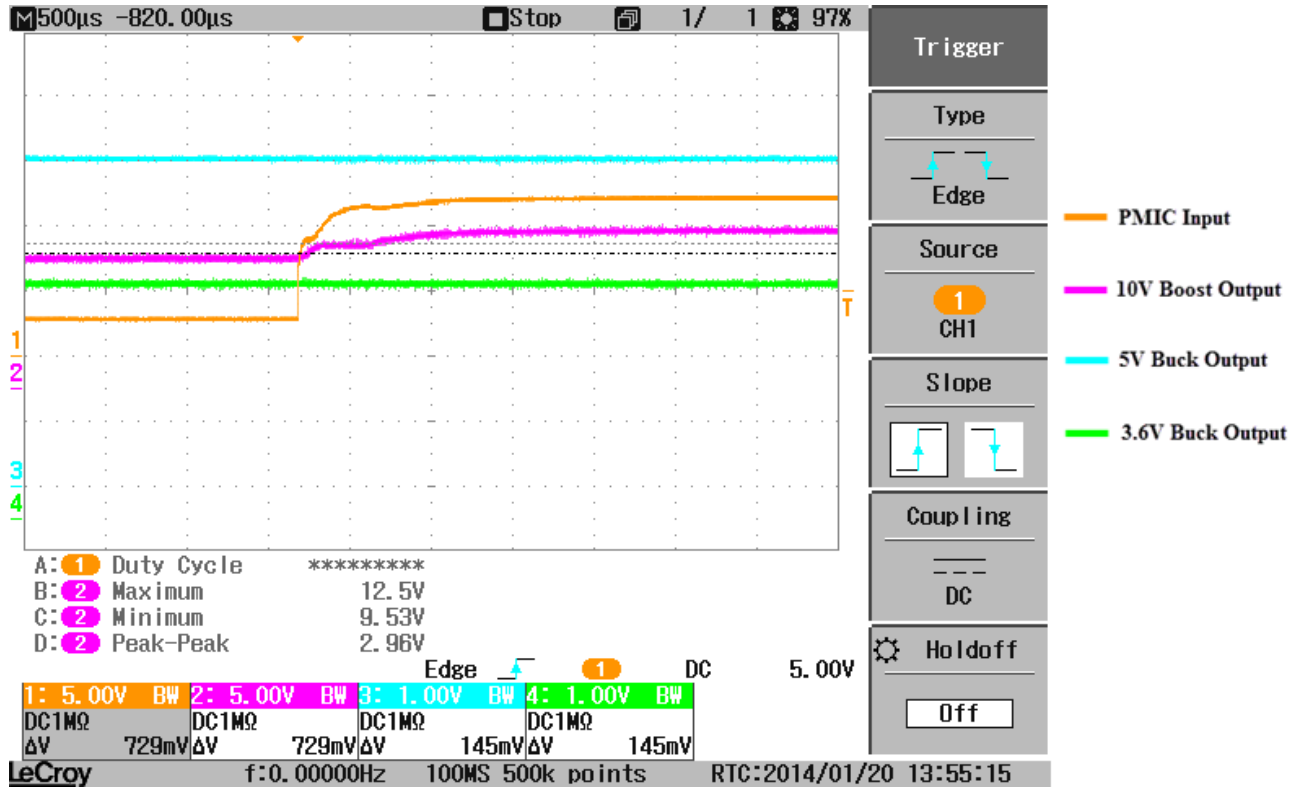
## E. Call off Backup Cell Battery

The following waveforms illustrate the PMIC Input, 10V Boost Converter Output, 5V Buck Converter Output, and 3.6V Buck Converter Output after a call was placed during operation off the backup cell battery.



## F. 12V Power Supply Reconnected

The following waveforms illustrate the PMIC Input, 10V Boost Converter Output, 5V Buck Converter Output, and 3.6V Buck Converter Output after the 12V Power Supply was reconnected to J6.



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